

Title (en)

HIGH-ENTROPY ALLOY AND METHOD FOR MANUFACTURING SAME

Title (de)

LEGIERUNG MIT HOHER ENTROPIE UND VERFAHREN ZUR HERSTELLUNG DAVON

Title (fr)

ALLIAGE À ENTROPIE ÉLEVÉE ET PROCÉDÉ DE FABRICATION D'UN TEL ALLIAGE

Publication

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Application

EP 20934927 A 20200512

Priority

KR 2020006209 W 20200512

Abstract (en)

[origin: EP4151766A1] A high-entropy alloy according to the present embodiment is a high-entropy alloy having an iron-rich phase and a copper-rich phase, and comprises a common complete solid solution metal that is completely solid-solved in iron and copper respectively. For example, the common complete solid solution metal may comprise nickel.

IPC 8 full level

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CPC (source: EP US)

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Citation (search report)

- [XII] DE 2031723 A1 19710107
- [XAI] KR 20200006906 A 20200121 - LG ELECTRONICS INC [KR], et al
- [XAI] US 2017275745 A1 20170928 - HONG SUN IG [KR], et al
- [A] CN 109252083 A 20190122 - ANYANG INST TECH, et al
- See references of WO 2021230392A1

Designated contracting state (EPC)

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EP 4151766 A1 20230322; EP 4151766 A4 20231220; US 2023183846 A1 20230615; WO 2021230392 A1 20211118

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